**Claims**

1. A device for producing a lens wafer (6) with a plurality of microlenses (15) with the following:

- an upper die (4) and a lower die (2) for embossing of the lens wafer (6) from a fluid embossing mass (9) which has been delivered between the dies (2, 4),
- curing means for curing of the embossed lens wafer (6),

wherein at least one release element (5, 5', 5", 5"', $5^{IV}$) for detachment of the cured lens wafer (6) prior to curing is located between the lower die (2) and the upper die (4), wherein the at least one release element (5, 5', 5", 5"', $5^{IV}$) is arranged laterally ~~between~~ at an edge around the dies (2, 4) and is introduced from a side of the dies (2, 4),

wherein the at least one release element (5, 5', 5", 5"', $5^{IV}$) contacts an unstructured surface (13, 14) of at least one die (2,4).

2. The device as claimed in Claim 1, wherein at least one of the dies (2, 4) comprises release depressions (16) corresponding to the shape of the phase sides (5s, 5s') of the release element (5, 5', 5", 5"', $5^{IV}$)

~~2~~3. The device as claimed in Claim 1, wherein the release element (5, 5', 5", 5"', $5^{IV}$) has an action section (12, 12') with one face side (5s, 5s') whose outside contour is shaped such that the action section (12, 12') can be located outside of the lower and/or upper lens molds (7, 8) in an unstructured region which is located especially on the periphery of the lower die (2) and/or of the upper die (4) for shaping of the microlenses (15).

~~3~~4. The device as claimed in Claim ~~2~~3, wherein the release element (5, 5', 5", 5"', $5^{IV}$) on the face side (5s, 5s') at least in the action section (12, 12') has an especially standard thickness (d) less than 2000 μm, preferably less than 1500 μm, still more preferably less than 1000 μm, most preferably less than 500 μm.

45. The device as claimed in at least one of the preceding claims, having at least one lower release element (5, 5', 5", 5"', $5^{IV}$) for contact with a peripheral section of the lower die (2) and one upper release element (5, 5', 5", 5"', $5^{IV}$) for contact with an especially spaced, preferably opposite peripheral section of the upper die.

56. A method for producing a lens wafer (6) with a plurality of microlenses (15) with the following steps, especially the following sequence:

- applying an embossing mass (9) to a lower die (2) or a wafer,
- placing at least one release element (5, 5', 5", 5"', $5^{IV}$) between the lower die (2) and an upper die (4) which is aligned relative to the lower die (2),
- embossing of the embossing mass (9) by the upper die (4),
- curing of the embossing mass (9),

characterized in that the placing proceeds prior to curing.

67. The method as claimed in Claim 56, wherein one action section (12, 12') of the release element (5, 5', 5", 5"', $5^{IV}$) is located in an unstructured region (14) of the upper die (4).

78. The method as claimed in Claim 56 or 67, wherein the lens wafer (6) after curing is detached from the lower die (2) and/or the upper die (4) by means of the release element (5, 5', 5", 5"', $5^{IV}$).